

CHIP



## 2024 TIDC Annual Meeting

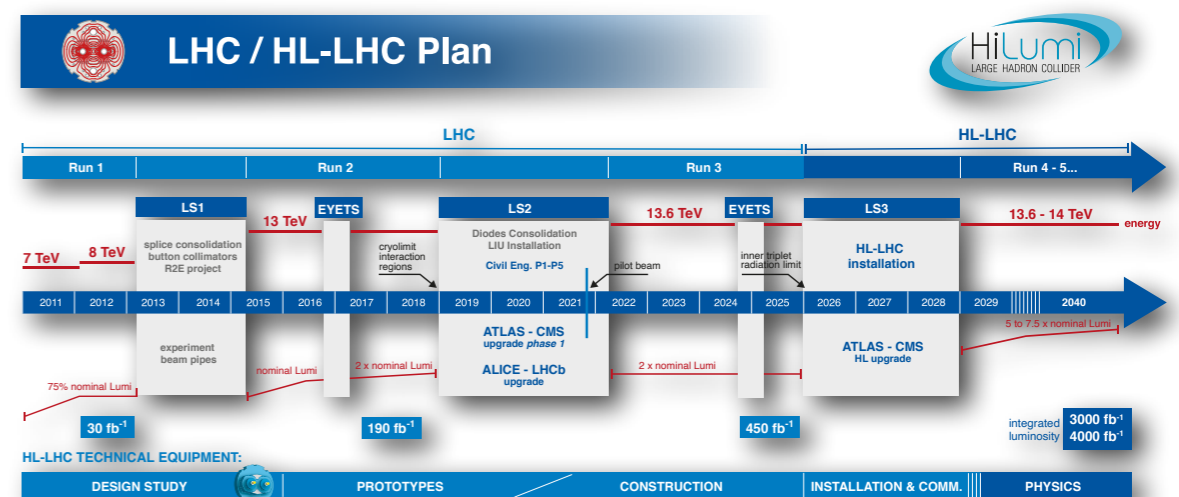
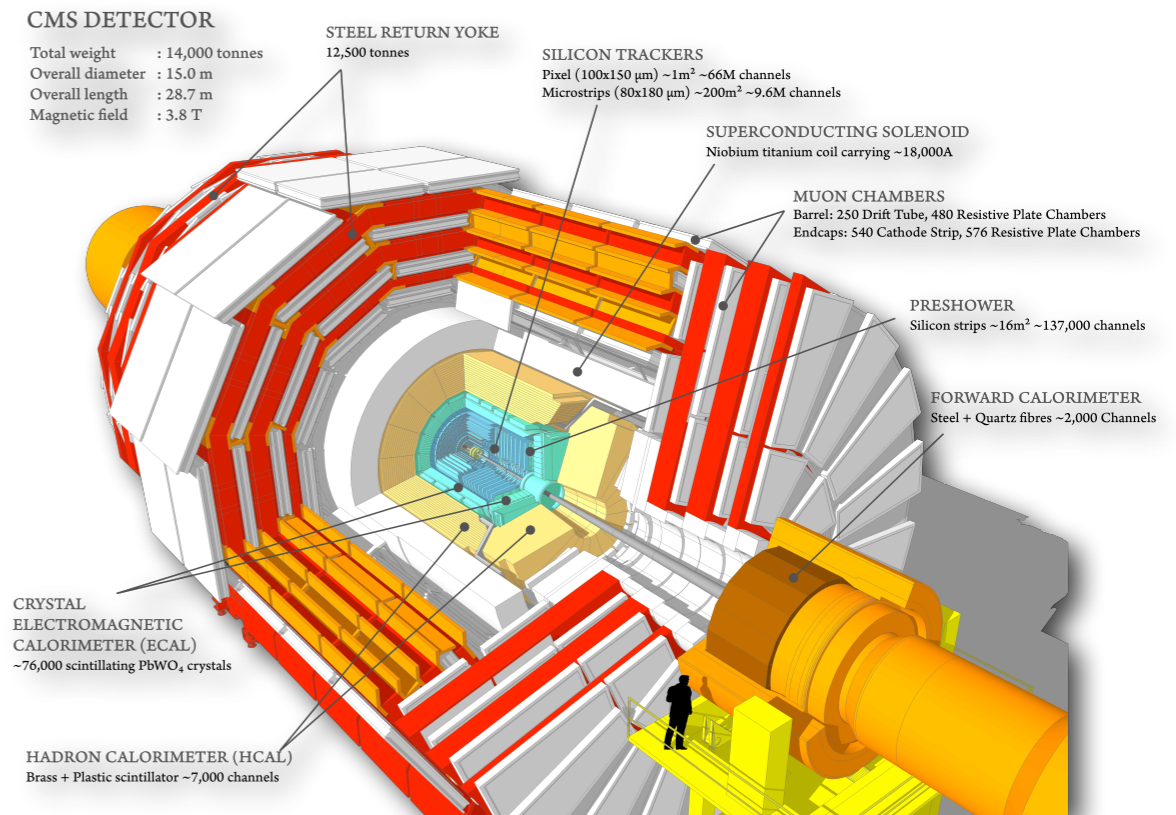
# Status of HGCAL SQC at NCU

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**National Central University, Taiwan**

**2024/11/22 TIDC Annual Meeting**

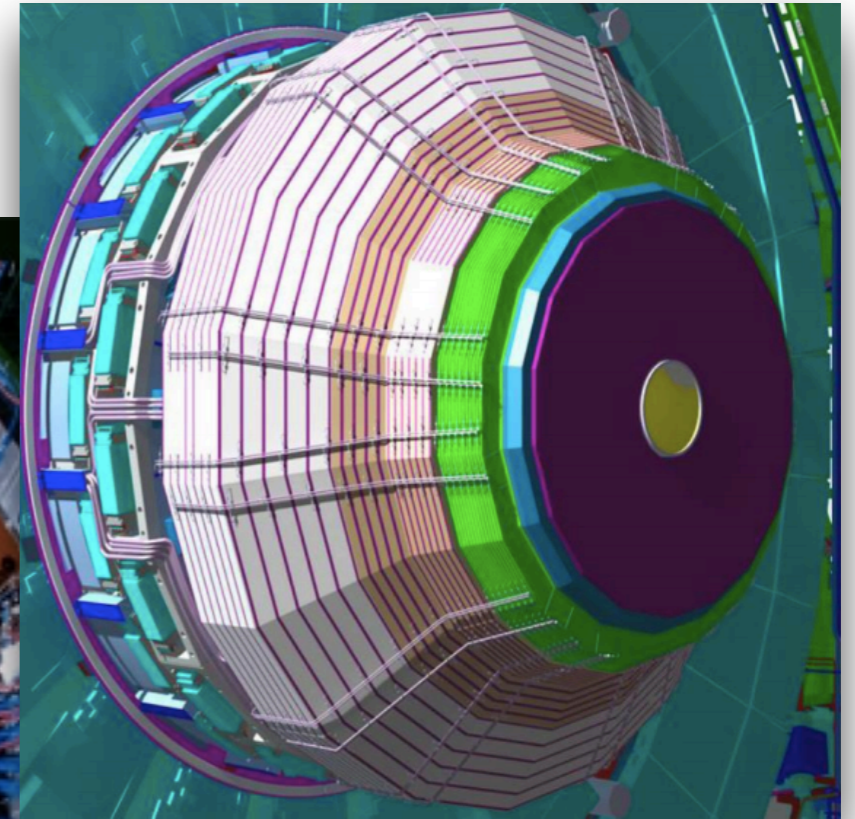
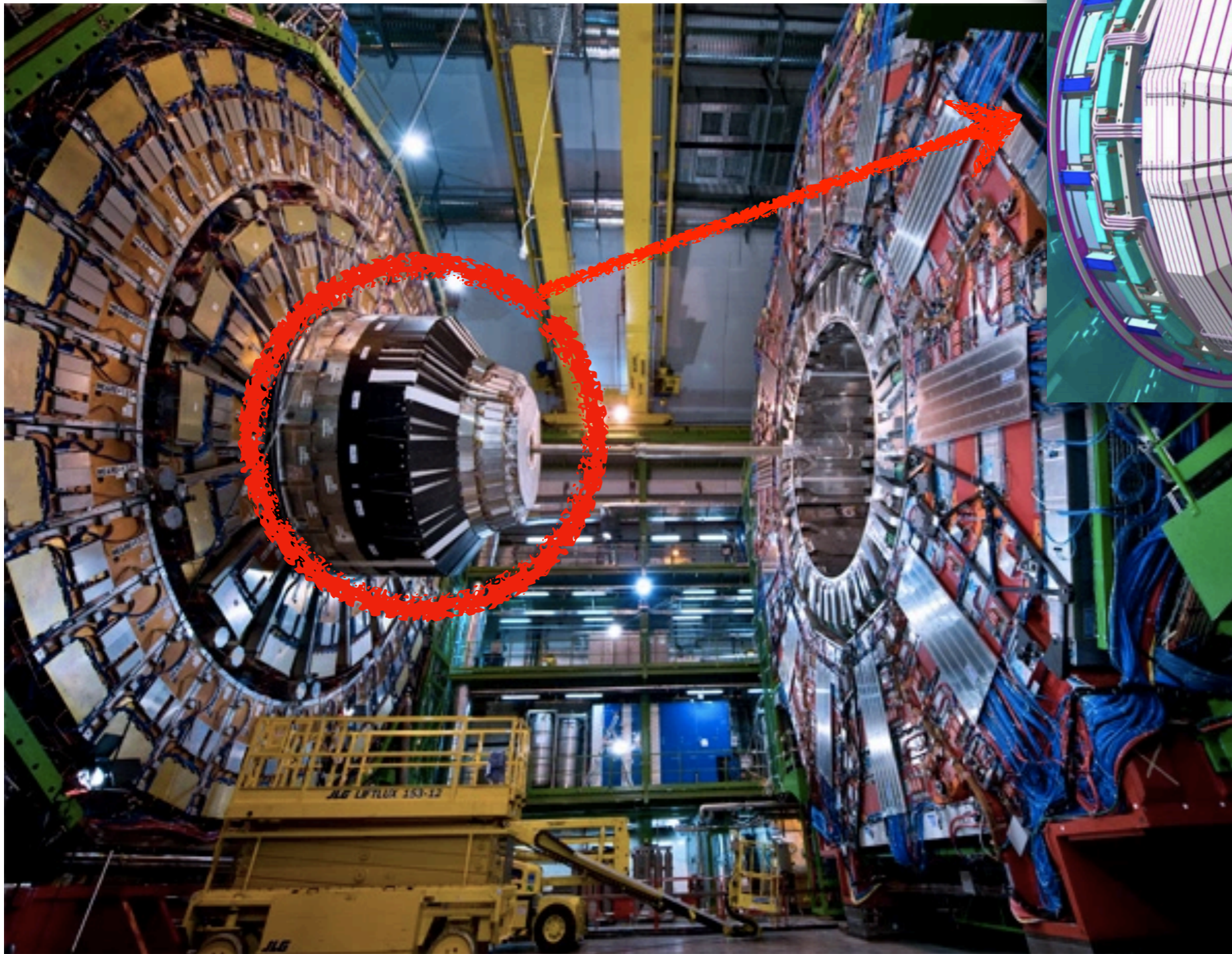
# Introduction

- High luminosity LHC(HL-LHC): Expected to start operation in 2029.
- ~10 times integrated luminosity.
- High pile up rate.
- High radiation levels : dose ~2 MGy
- CMS collaboration is designing a new high granularity calorimeter (HGCal) which will be built and replace existing End-cap calorimeters in around 2026.





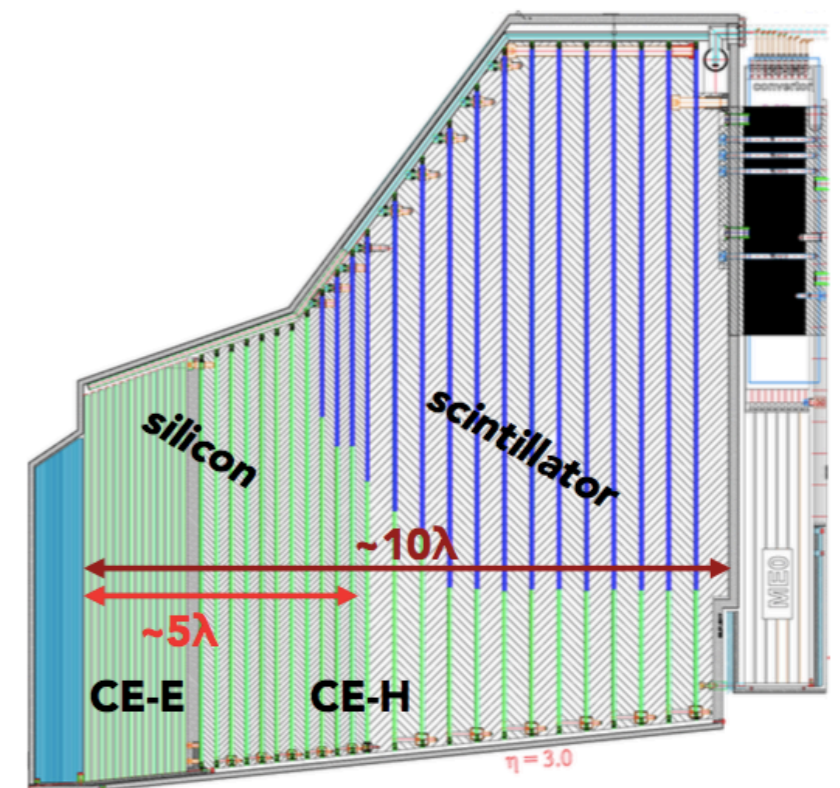
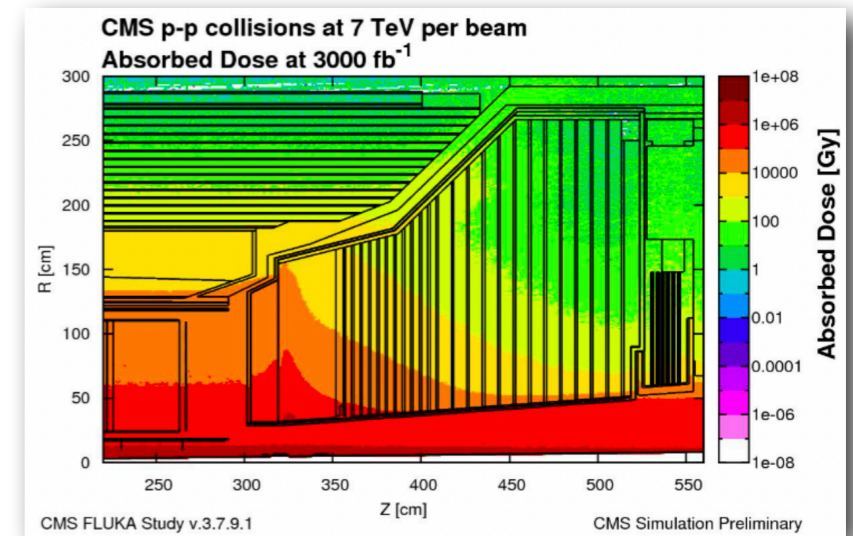
# HGCAL





# HGCAL sensors

- HGCAL
  - Active layers :
    - CE-E - silicon
    - CE-H - mixed layers of silicon & scintillator
  - Key parameters :
    - $\sim 600 \text{ m}^2$  silicon sensors produced on 8-inch wafers
    - There are three different thicknesses :  $300 \mu\text{m}$ ,  $200 \mu\text{m}$  and  $120 \mu\text{m}$



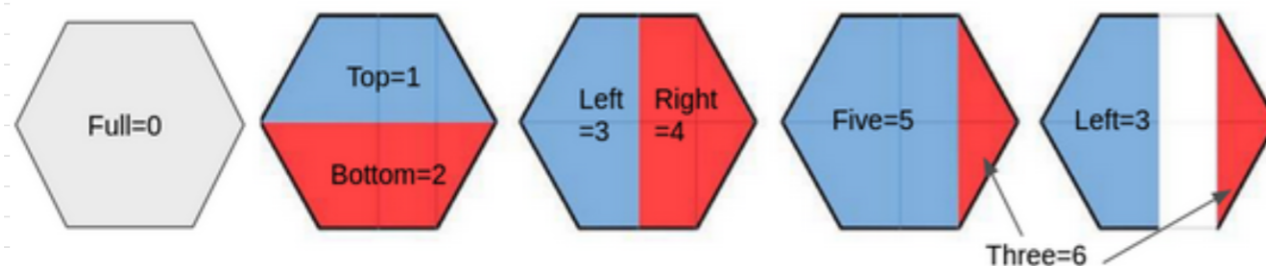
	Silicon	Scintillators
Area	$\sim 600 \text{ m}^2$	$\sim 500 \text{ m}^2$
Channel size	$0.5 - 1.0 \text{ cm}^2$	$4 - 30 \text{ cm}^2$
Modules	$\sim 30000$	$\sim 4000$
Channles	$\sim 6 \text{ M}$	$\sim 240 \text{ k}$



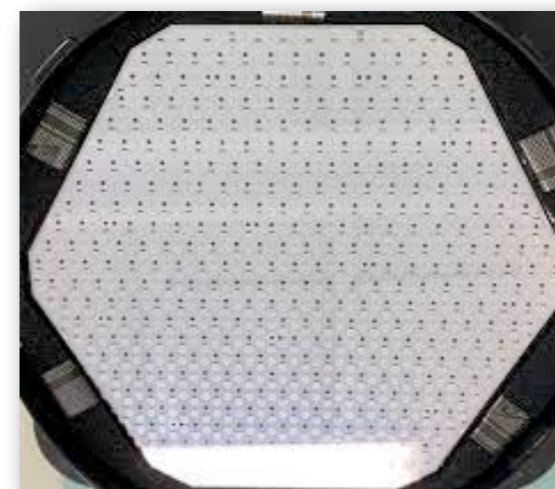
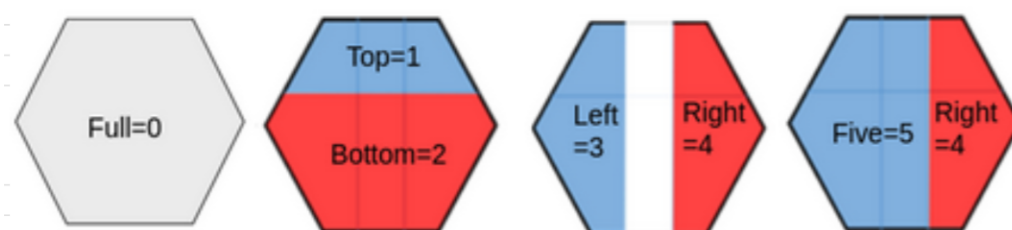
# HGCAL SQC

- HGCAL sensors quality control (HGCAL SQC) :
  - There are 4 HGCAL SQC centers : CERN, FSU, NCU, TTU.
- There are different types of silicon sensors according to the silicon shape and its channel number.
  - NCU currently only received LD full sensors and HD full sensors.
- HGCAL SQC steps :
  - Sensor Alignment (along with contact test)
  - IV measurement & CV measurement

LD partial sensor layout names



HD partial sensor layout names



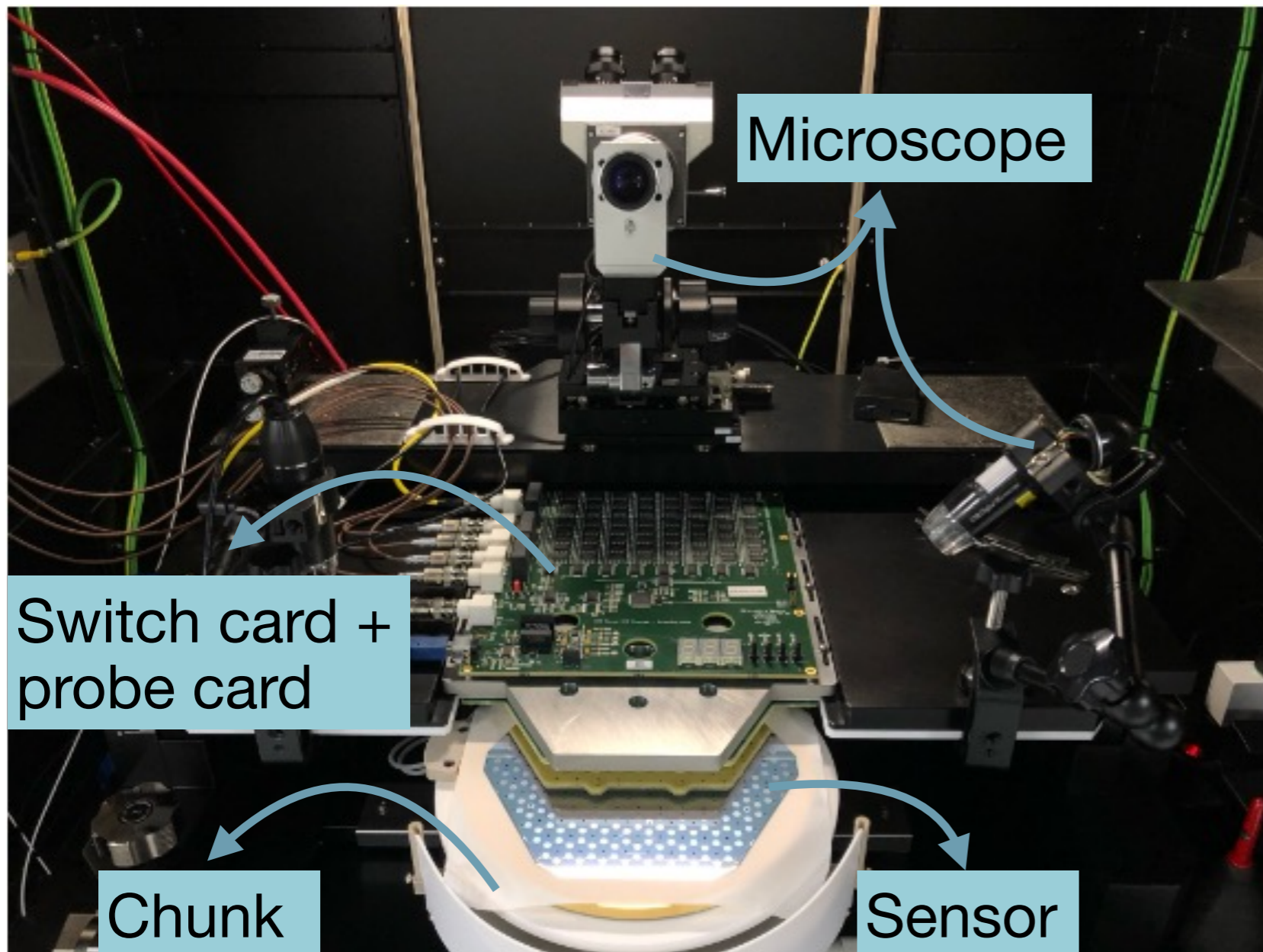
HD full sensor



LD full sensor

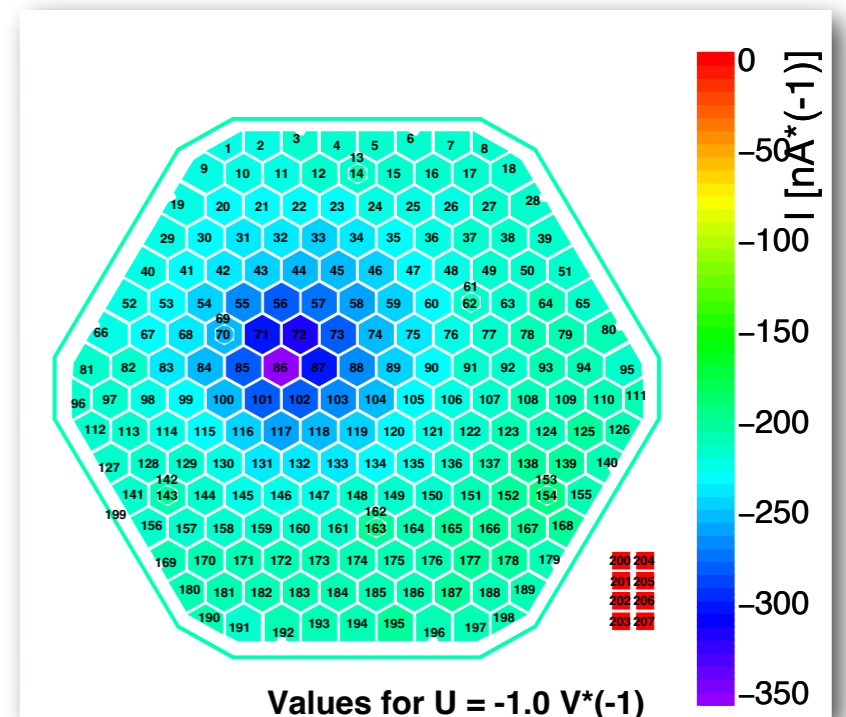
# Setup

- The microscope is used for the sensor alignment.
- To ensure the good sensor alignment, the contact test is performed.



IV @ 1V forward bias: to test if all pins have contact.

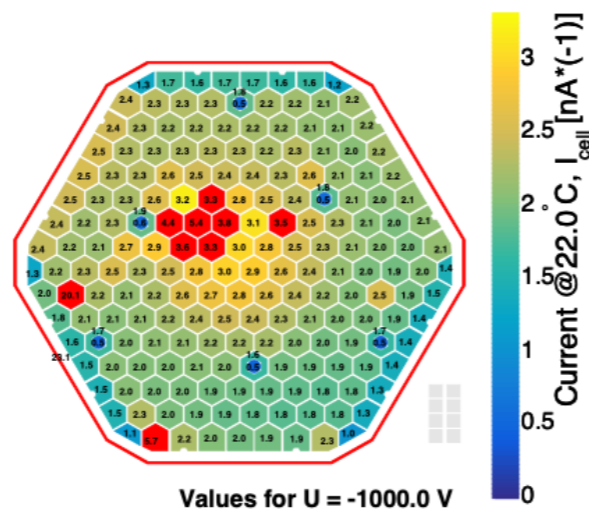
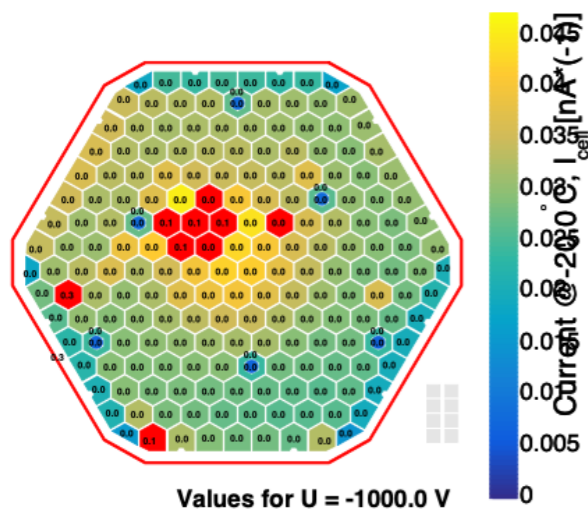
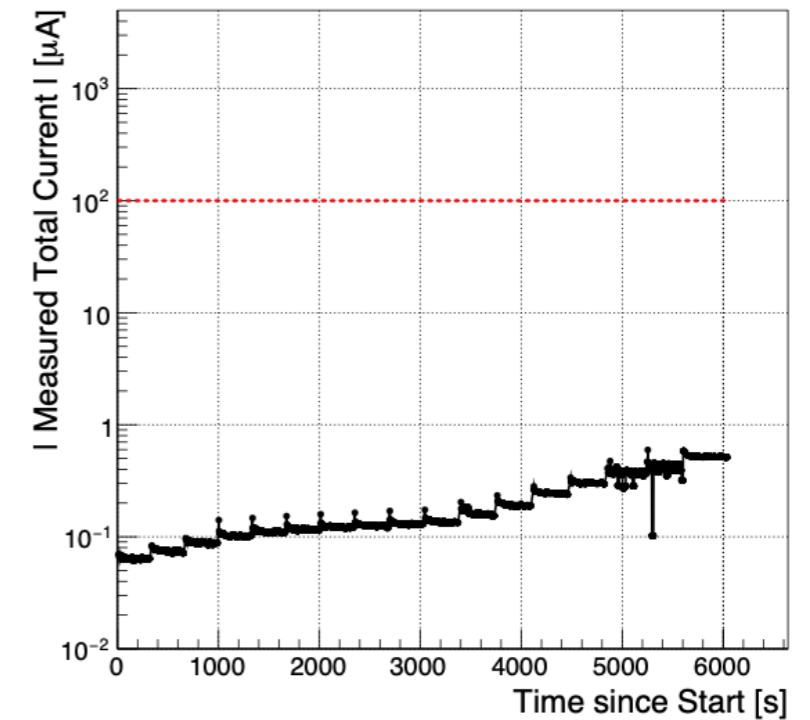
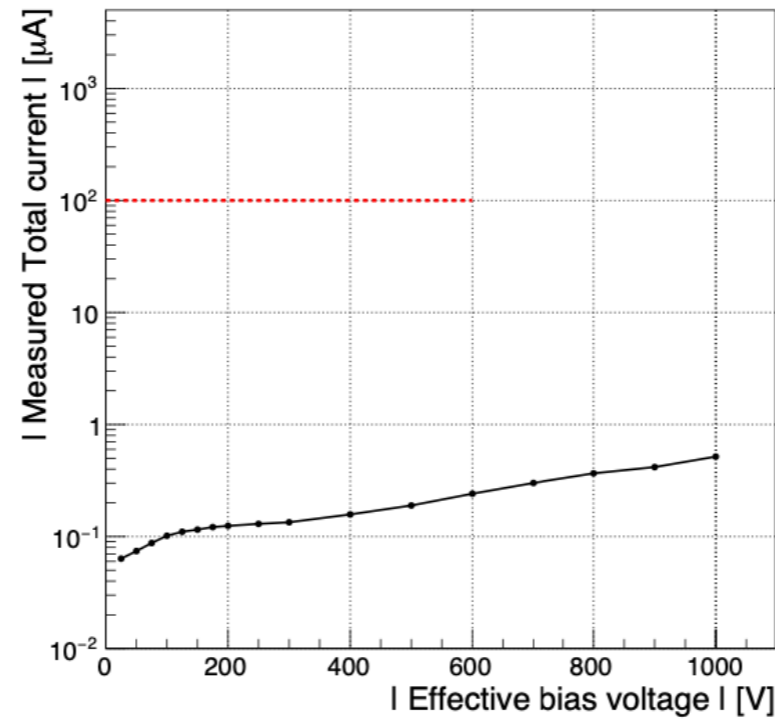
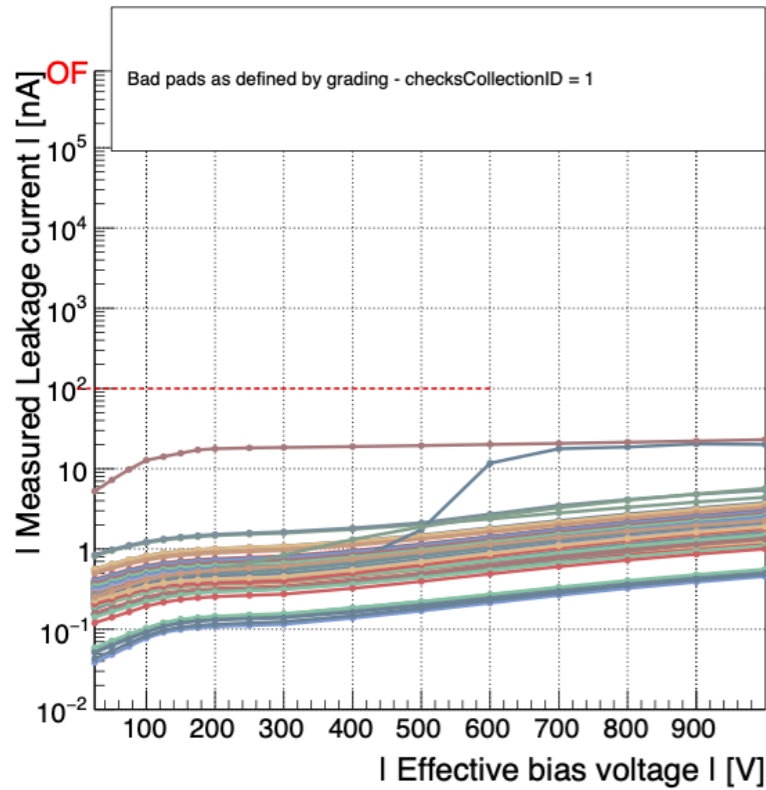
All cells have ~200nA forward bias current





# IV measurement results

Sensor: 102004, 300 $\mu\text{m}$  LD



## Grading:

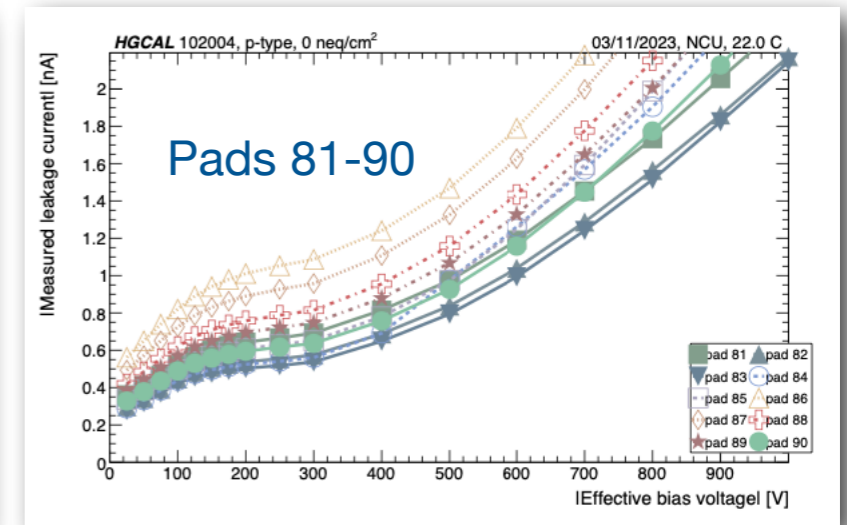
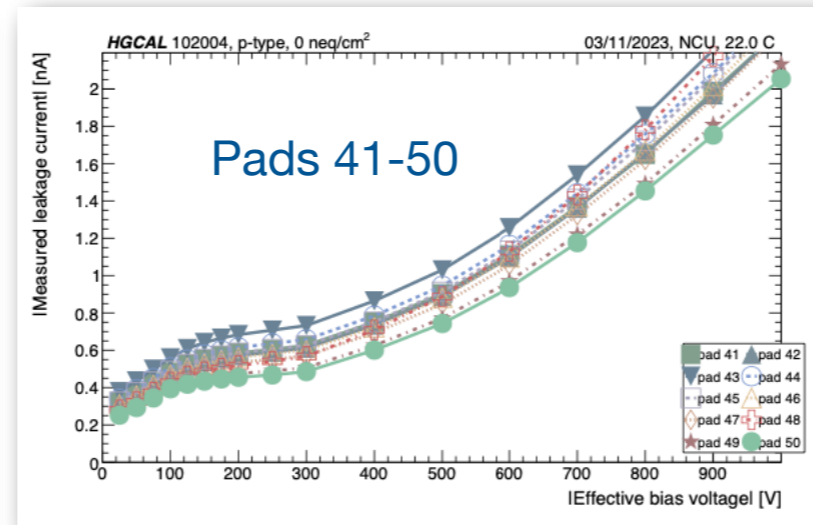
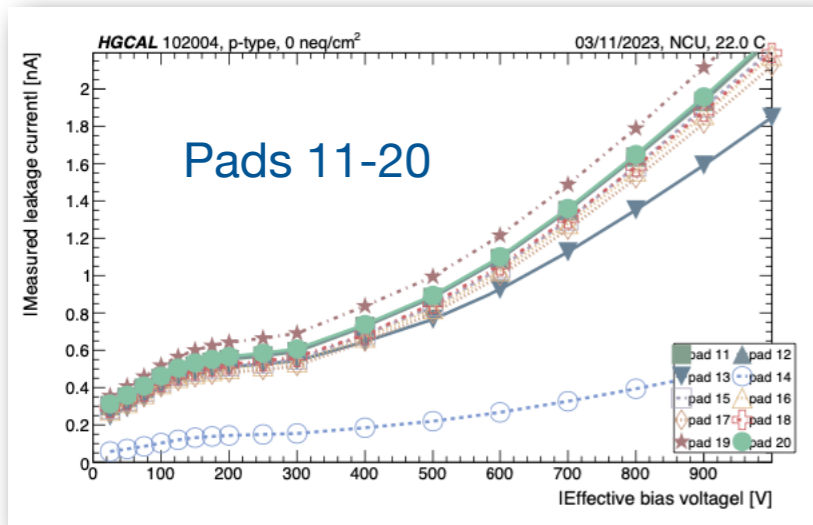
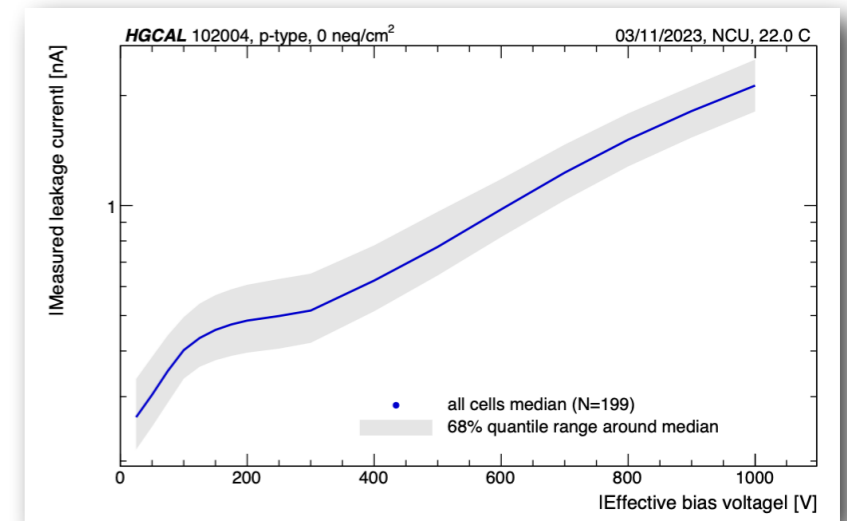
- Sensor has been graded with checksCollectionID 1.
- Global characteristics:
  - Current at 600V I600 (normalised to 20 deg Celsius):  $\leq 100 \mu\text{A}$  integrated over the sensor and guard rings: **Passed**
  - $I800 < 2.5 \times I600$ : **Passed**
  - Number of bad pads  $0 \leq 8$  for full-sized sensors: **Passed**
  - Allowed number of adjacent bad pads  $\leq 2$ : **Passed**
- Per-pad characteristics used to define bad pads if any of the following are met:
  - Current at 600V I600 (normalised to 20 deg Celsius)  $> 100 \text{ nA/pad}$ : **0** pads, namely []
  - $I600 > 10 \text{ nA}$  and  $I800 > 2.5 \times I600$ : **0** pads, namely []
  - $I600 \leq 10 \text{ nA}$  and  $I800 > 25 \text{ nA}$ : **0** pads, namely []

Sensor has **PASSED** the requirements.

# IV measurement results

Sensor: 102004, 300 $\mu\text{m}$  LD

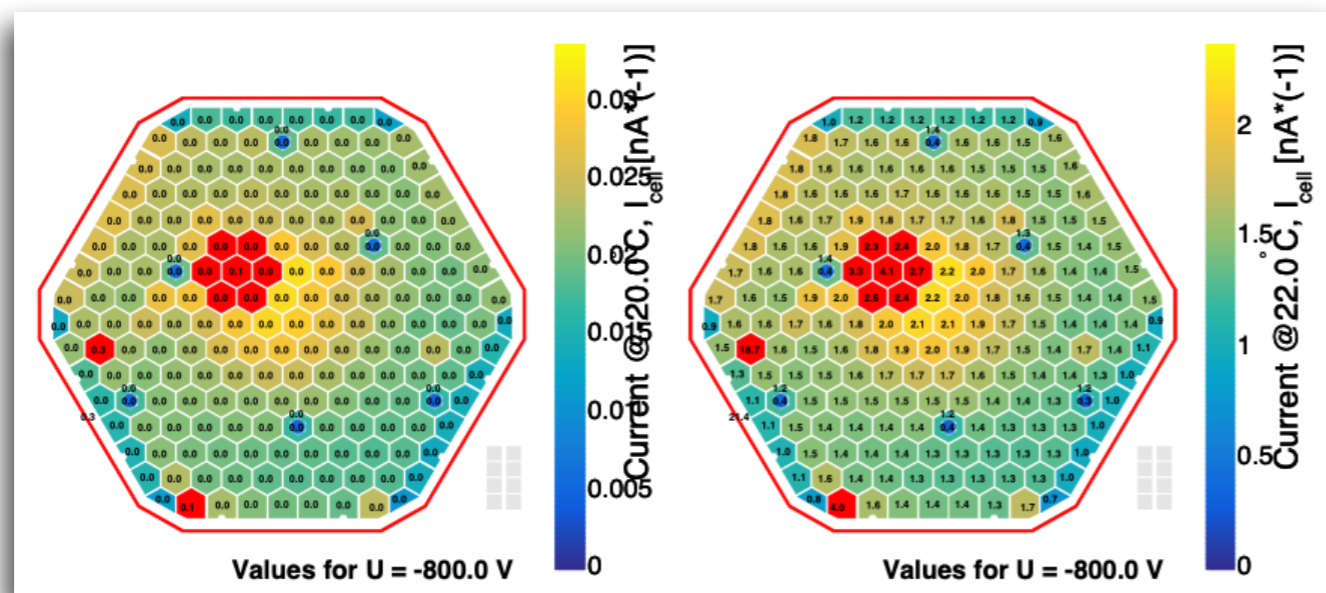
- IV curve per cell results.
- The individual cell currents show expected trend with increasing voltage.
- Looking particularly at the hot regions also confirms that the voltage dependency of the currents are of the same characteristic as for the other cells.





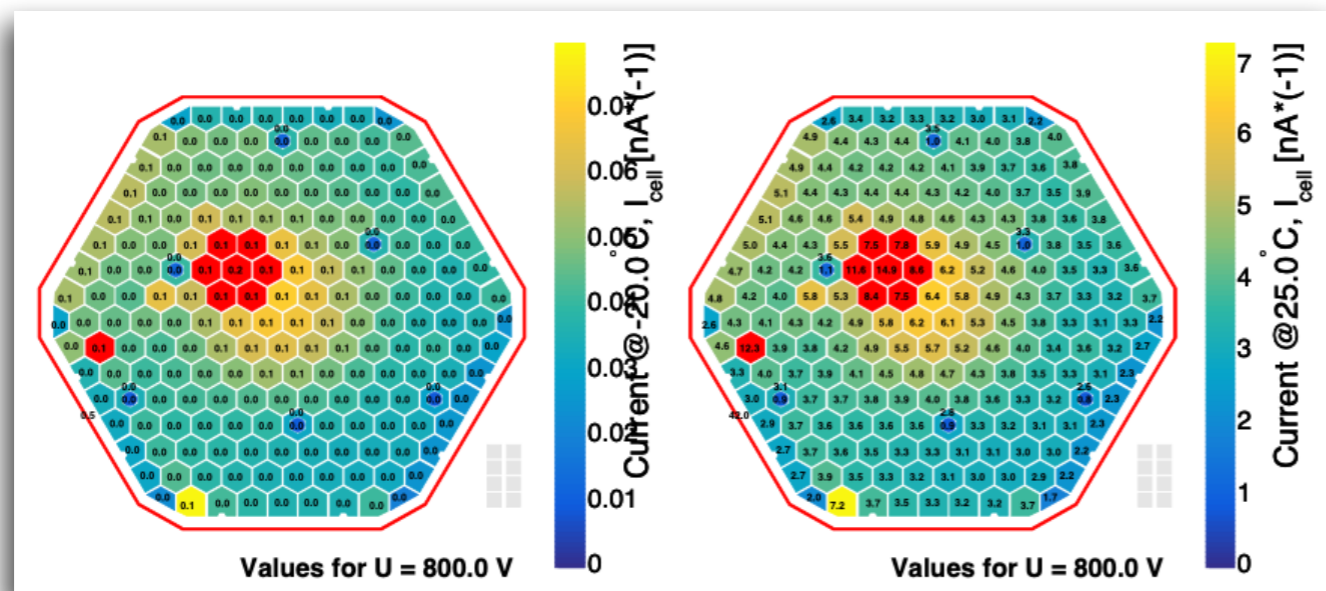
# Compare results to Hamamatsu

- We compared the results of the same sensor measured at Hamamatsu.
- The testing results are similar to our results.



Sensor: 102004, 300 $\mu$ m LD

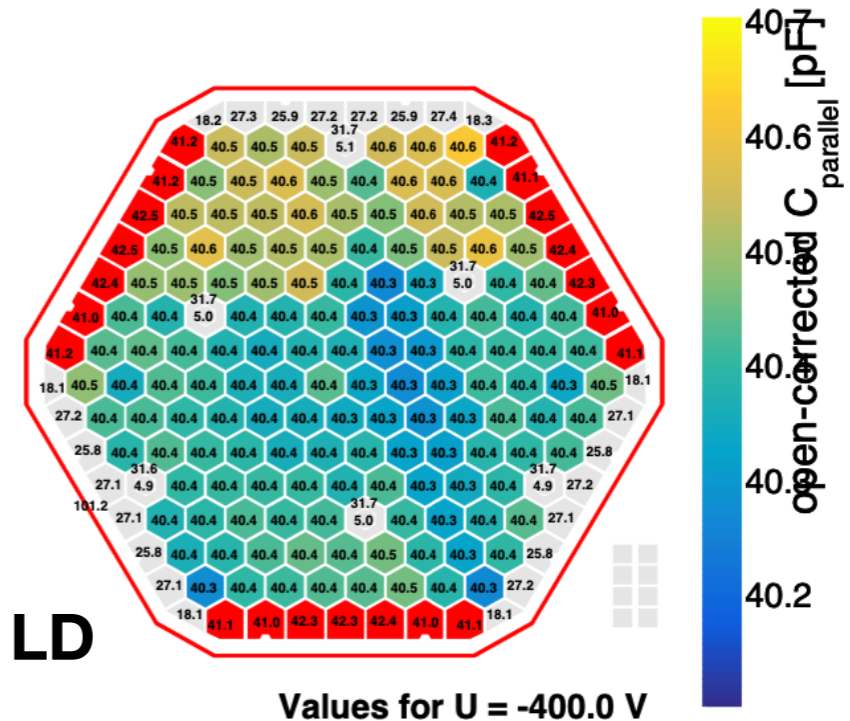
@ NCU



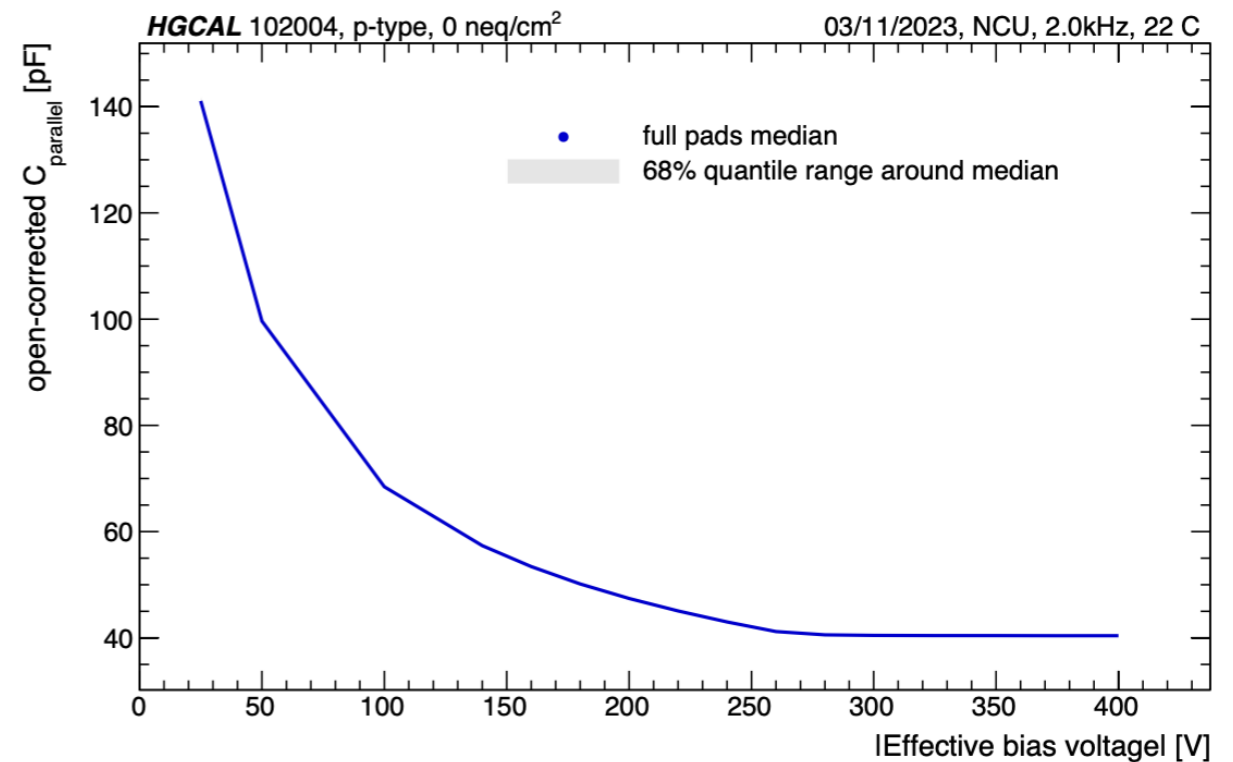
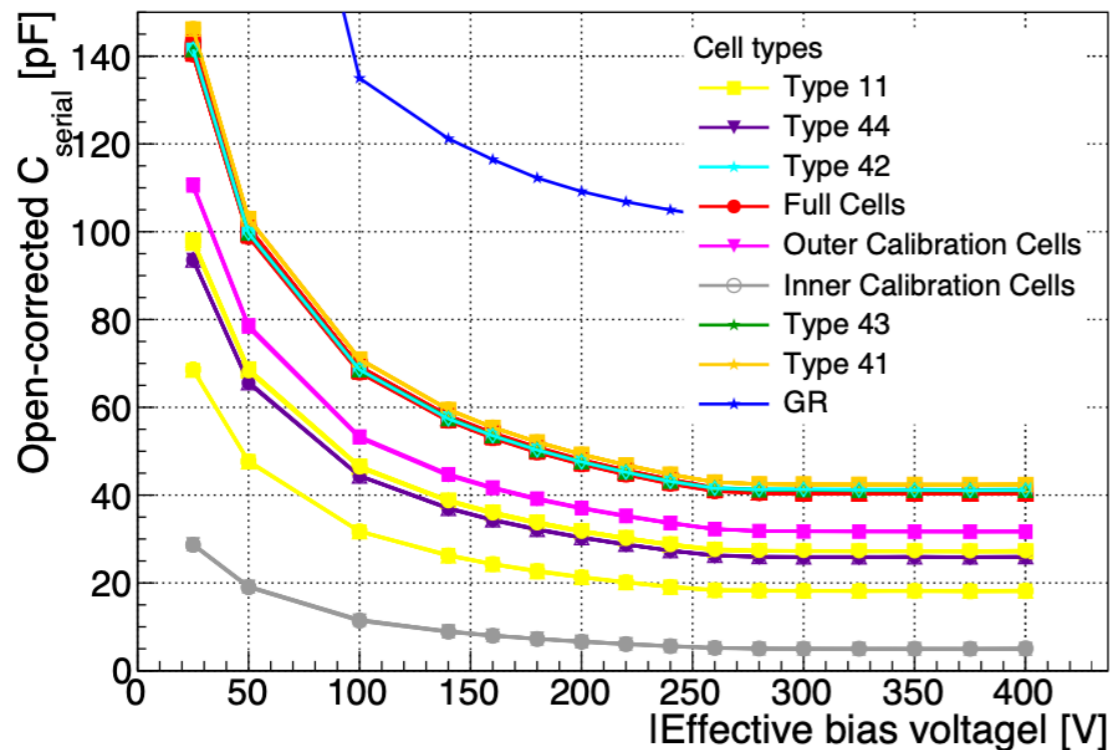
@ Hamamatsu

# CV measurement results

- The CV characteristic also has been checked.
- The CV characteristic behaved as expected.



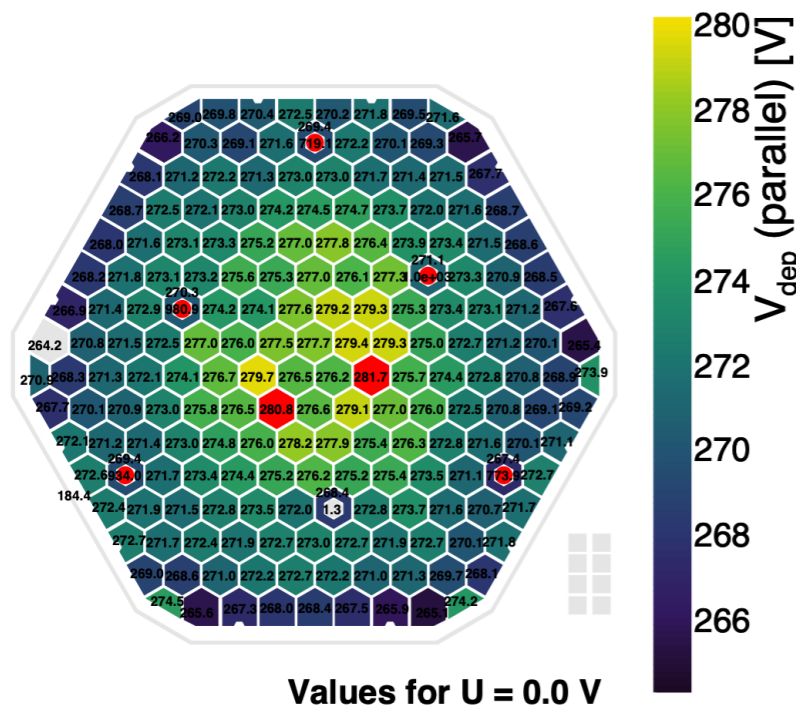
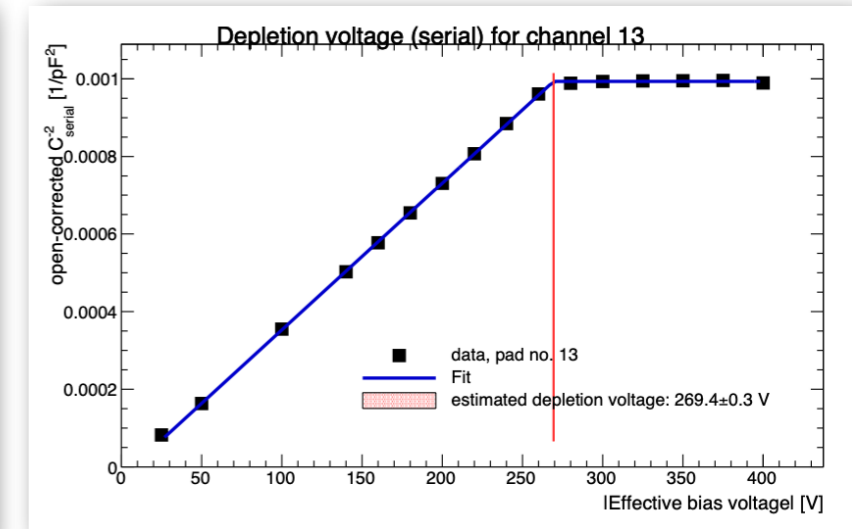
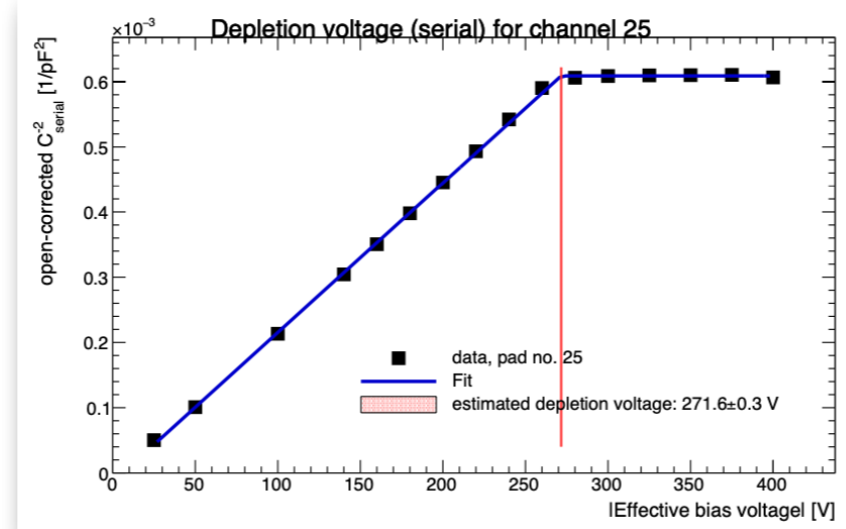
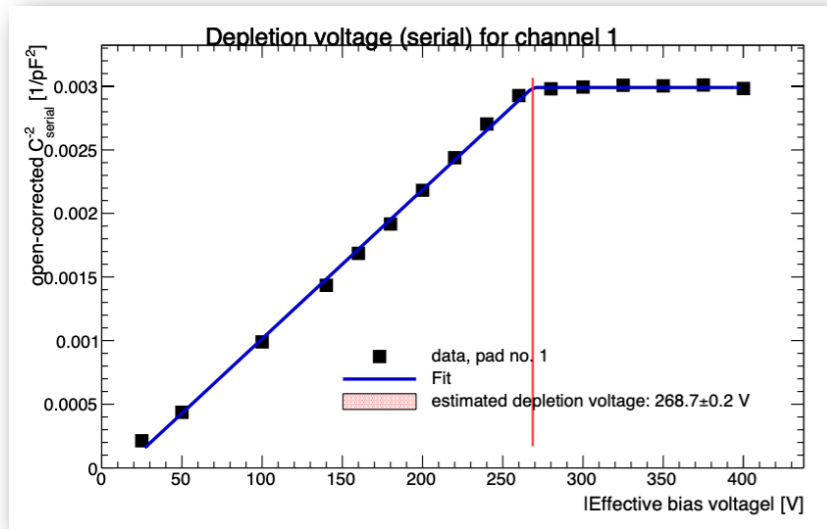
Sensor: 102004,  $300\mu\text{m}$  LD





# CV measurement results

Sensor: 102004, 300 $\mu\text{m}$  LD



- Global characteristics using FULL cells only:

- Full depletion voltage  $V_{\text{dep}} = 273.0$  V calculated as the median of depletion voltages across cells, after removing outliers outside quantile 16-84%.
- $V_{\text{dep}} < 370$  V for sensor of assumed thickness of 300  $\mu\text{m}$ : **Passed**
- Variation across sensor  $\Delta V_{\text{dep}} = 0.7$  %
- $\Delta V_{\text{dep}} \leq$  Maximum variation across sensor of  $\pm 10\%$  for sensor of  $V_{\text{dep}} = 273.0$  V: **Passed**

- Per-pad characteristics using FULL cells only:

- $C_{\text{meas\_mean}} = 40.461$  pF, computed as the measured open corrected serial capacitance averaged over cells

- Thickness uniformity across sensor using FULL cells only:

- Relative thickness variation  $\Delta \text{thickness} = 0.2$  %  $< 10 / 300$ : **Passed**

Sensor has **PASSED** the requirements.

# SQC status

- In total we received **3325** LD sensors and **322** HD sensors.
- In total **168** LD sensors and **32** HD sensors were tested and passed the criteria.

Shipping date	Production round	Thickness	Number of sensors	Number of sensors to be measured (5%)	Number of sensors	IV passed	CV passed
March, 2023	Production	300 um	73	~4	4	4	4
July, 2023	Production	300 um	1142	~57	57	57	57
November, 2023	Production	300 um	1443	~73	73	73	73
January, 2024	Production	120 um	132	~7	16	16	16
April, 2024	Production	120 um	96	~5	8	8	8
May, 2024	Production	300 um	667	~33	38	38	38
May, 2024	Production	120 um	94	~5	8	8	8
July, 2024	Production	120 um	191	~10	On going	NaN	NaN

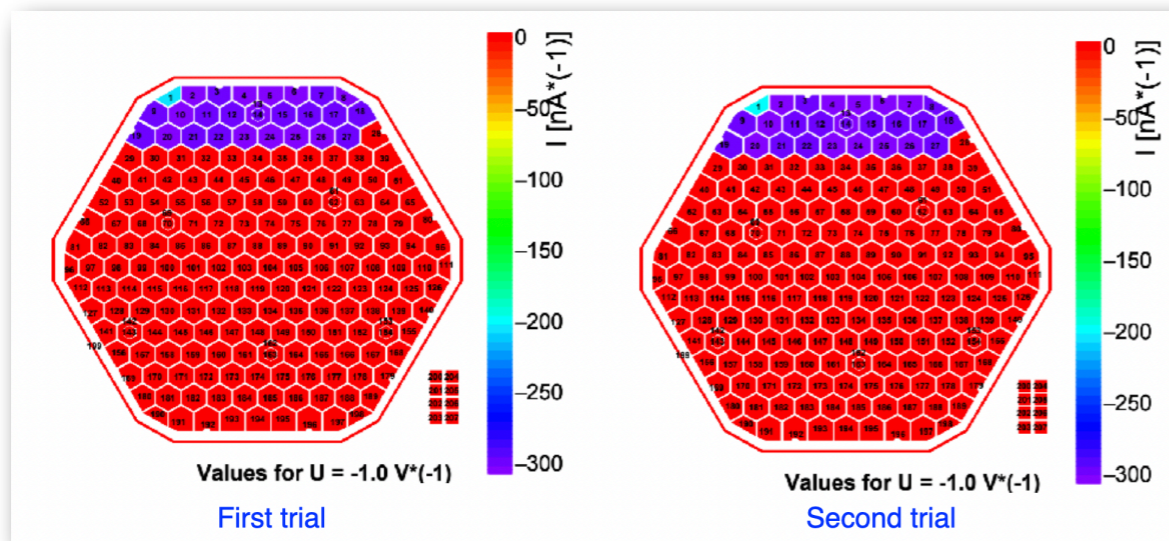
**SQC measurement rate : ~3 /working days**



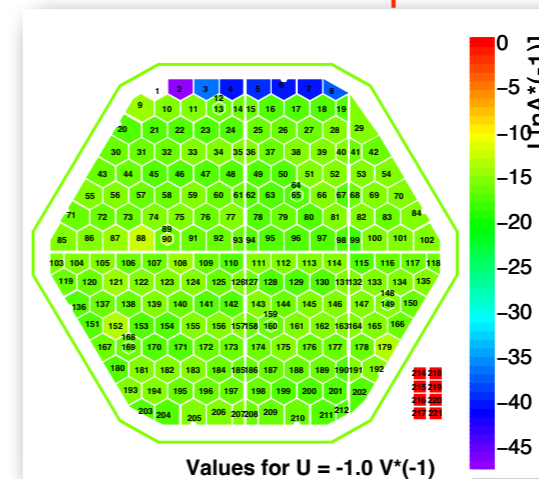
# Contribution in software

- The LabView control system setup for the picometer *Keithly 6517* was not properly developed as CERN or any other sensor testing station doesn't use it.
- We contributed in updating the LabView software setup to correctly incorporate *Keithly 6517* in the testing system.

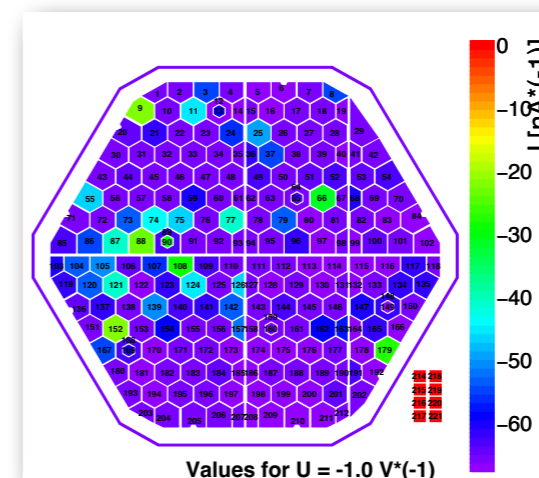
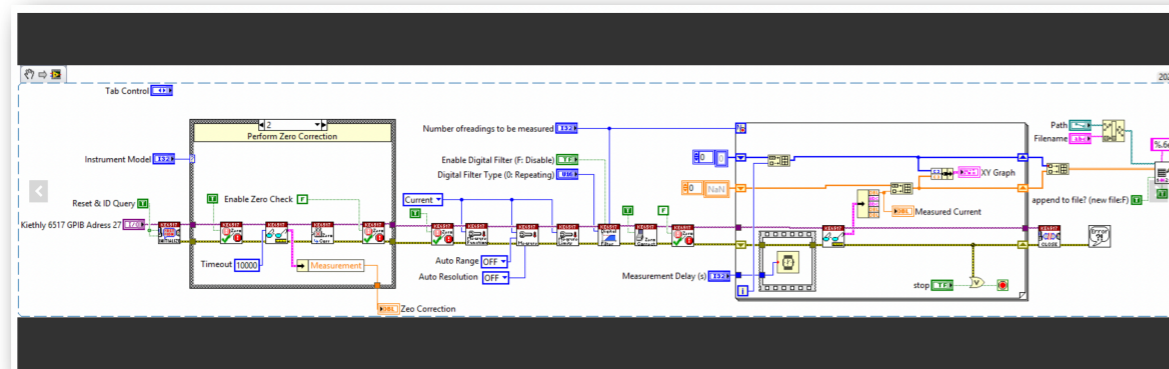
Contact test before software development



Contact test comparison after software development



Measurements with picometer 6517b (The one NCU used)



Measurements with picometer 6487 (Standard one CERN uses)

# Summary

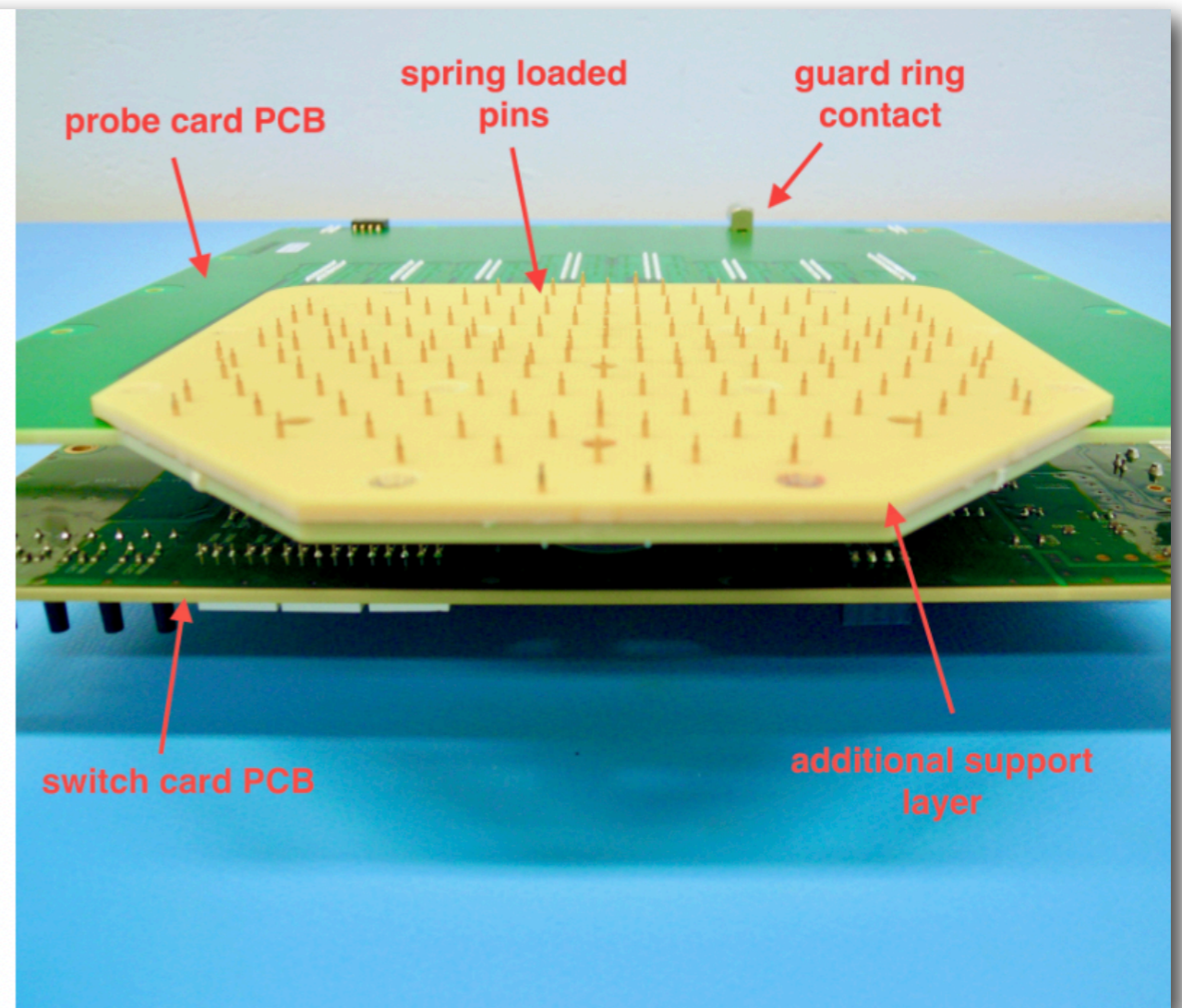
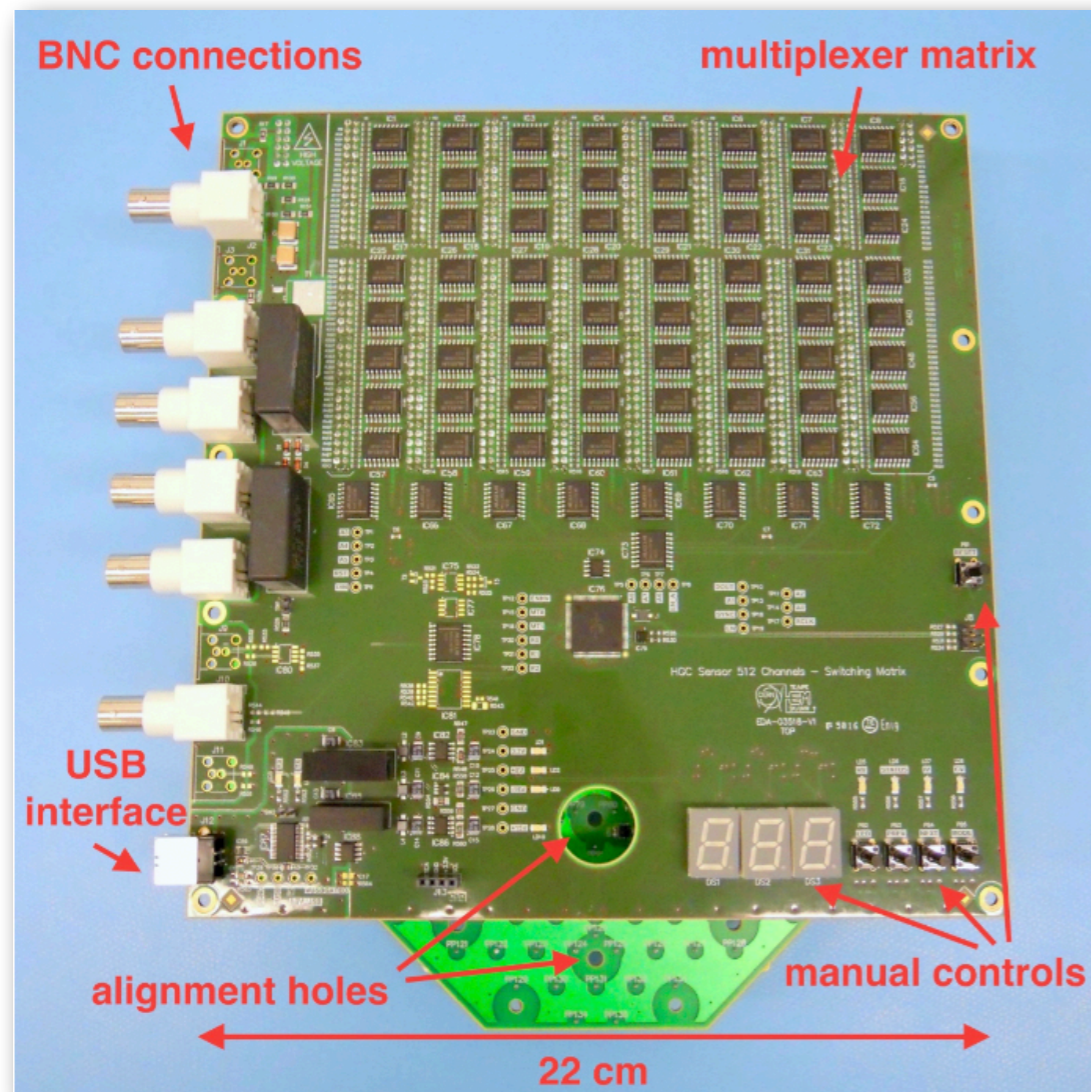
- NCU is fully functional in HGICAL SQC now.
- From production campaign we received **3325** *300  $\mu\text{m}$  LD full sensors* and **322** *120  $\mu\text{m}$  HD full sensors* at NCU.
- Measured  $\sim 5\%$  of all the sensors.
- Average measurement rate :  $\sim 2$  sensors per day
- Contributed in the testing system software for the measurement instruments.
- Future work :
  - *563 300  $\mu\text{m}$  LD full sensors & 94 120  $\mu\text{m}$  HD full sensors* will arrive at NCU in recent future.
  - Raise the measurement rate up to 8%.



**Back up**

# Testing platform

- We used a probe card (right figure) as a probing tool to the sensor and use a switch card (left figure) as readout controller board.

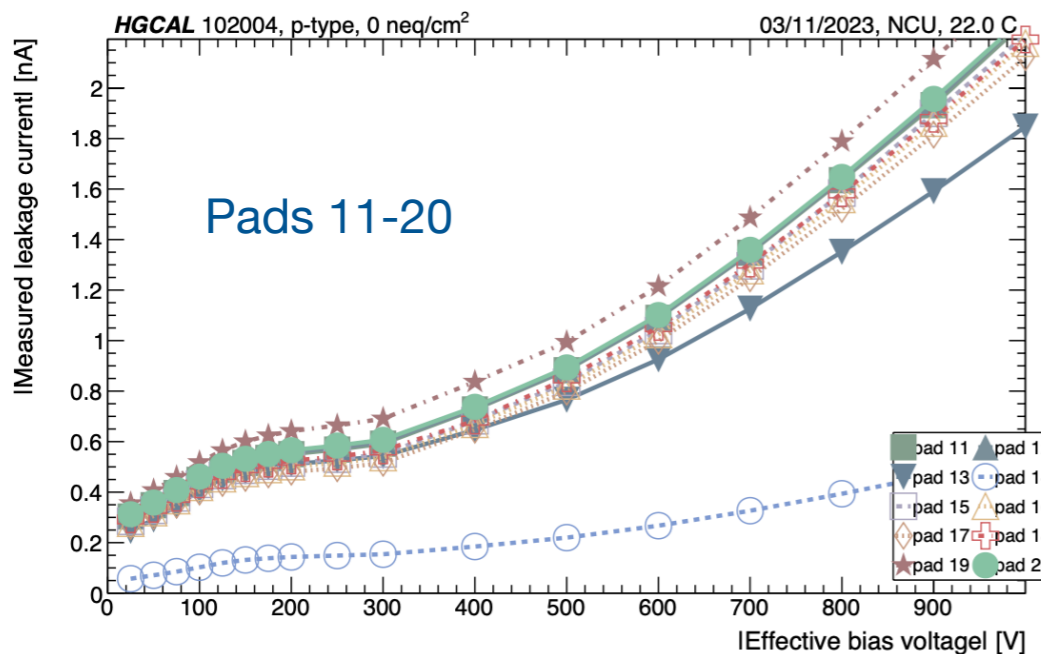
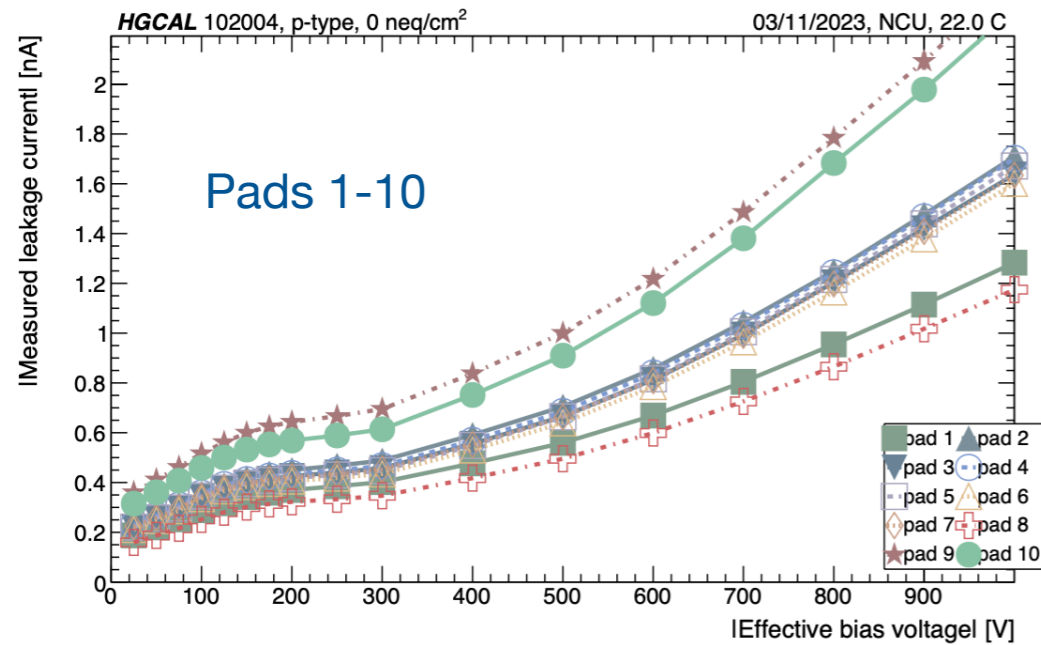




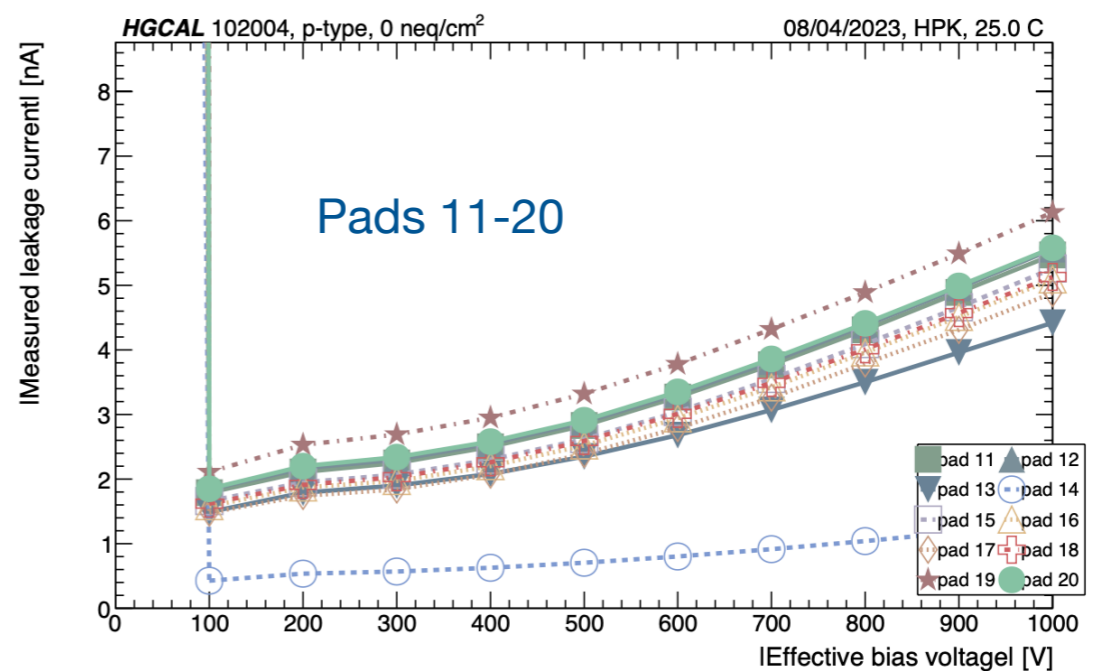
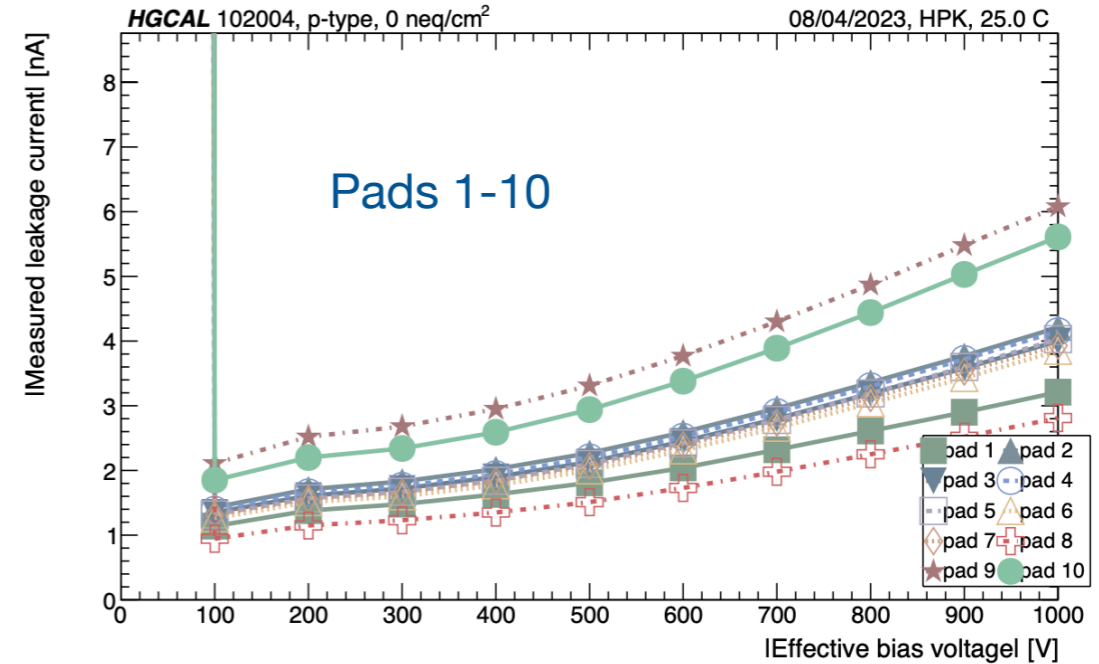
# Comparison with Hamamatsu

Sensor: 102004,  $300\mu\text{m}$  LD

@ NCU



@ Hamamatsu



# Analysis framework

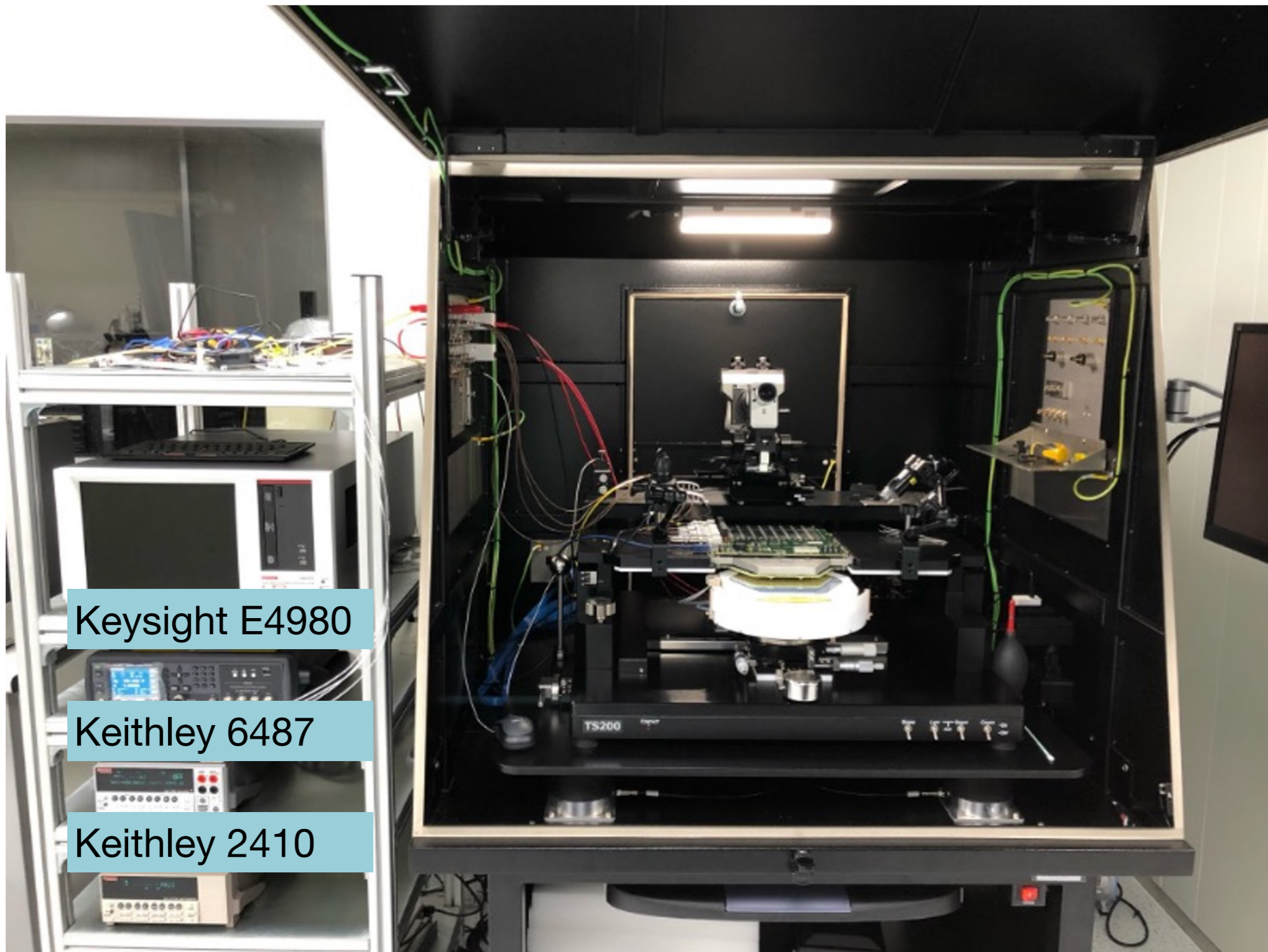
- Gitlab link for IVCV analysis framework:
  - [https://gitlab.cern.ch/CLICdp/HGCAL/lcd\\_hgcal\\_analysisworkflows](https://gitlab.cern.ch/CLICdp/HGCAL/lcd_hgcal_analysisworkflows)
- The requirements for non-irradiated sensors:

## ChecksCollectionID 1

The vendor specifications for non-irradiated HGC silicon sensors.

- All pads (full hexagons and special geometries),  $I_{\text{pad\_increase}}$  requirement with 10nA threshold, different increase requirements for pads with more or less than 10nA of leakage current.
- Global characteristics based on total leakage current:
  - Current 600V I600 (normalised to 20 deg Celsius):  $\leq 100$  uamp integrated over the sensor and guard rings
  - $I_{800} < 2.5 \times I_{600}$
- Per-pad characteristics for all (i.e. full hexagons and special geometries) pads:
  - Current @600V I600 (normalised to 20 deg Celsius):  $\leq 100$  nA/pad
  - if  $I_{600} > 10$  nA:  $I_{800} < 2.5 \times I_{600}$
  - else if  $I_{600} \leq 10$  nA:  $I_{800} < 25$ nA
- Location of bad pads and clustering:
  - $\leq 8$  bad pads for full-sized sensors
  - not more than two adjacent bad pads

# Setup & Instruments



Keysight E4980

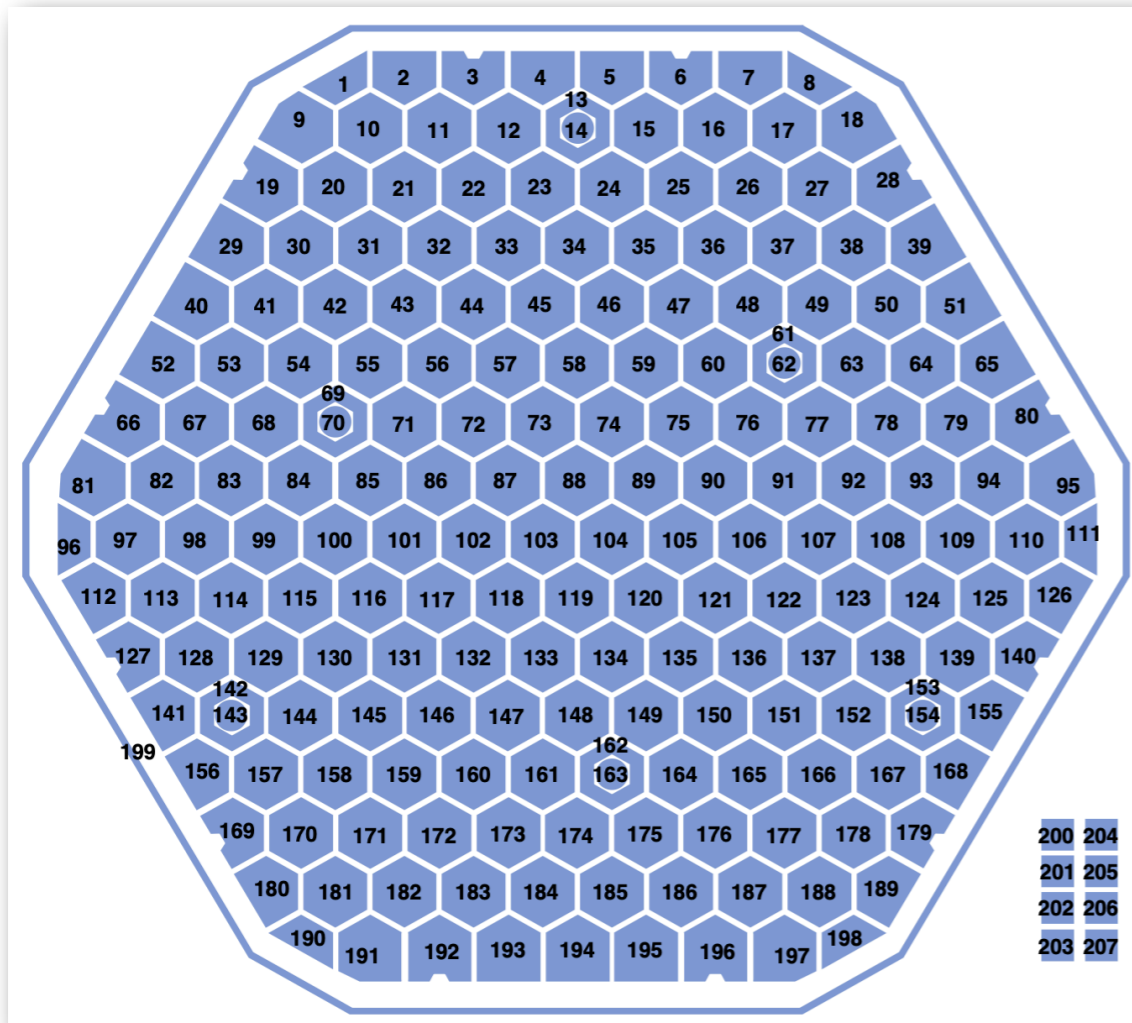
Keithley 6487

Keithley 2410

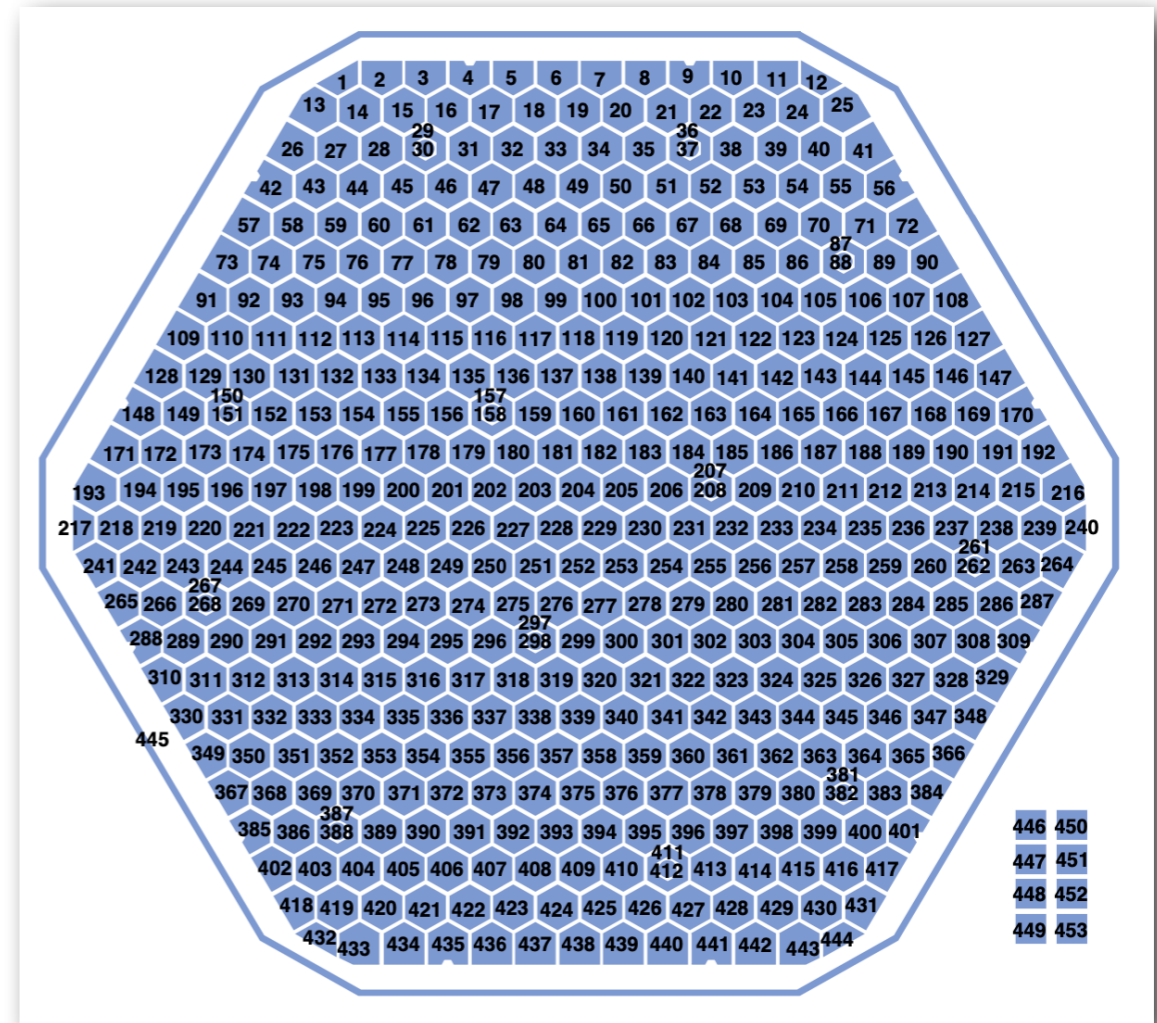


# Channel mapping

## LD full sensor channel map

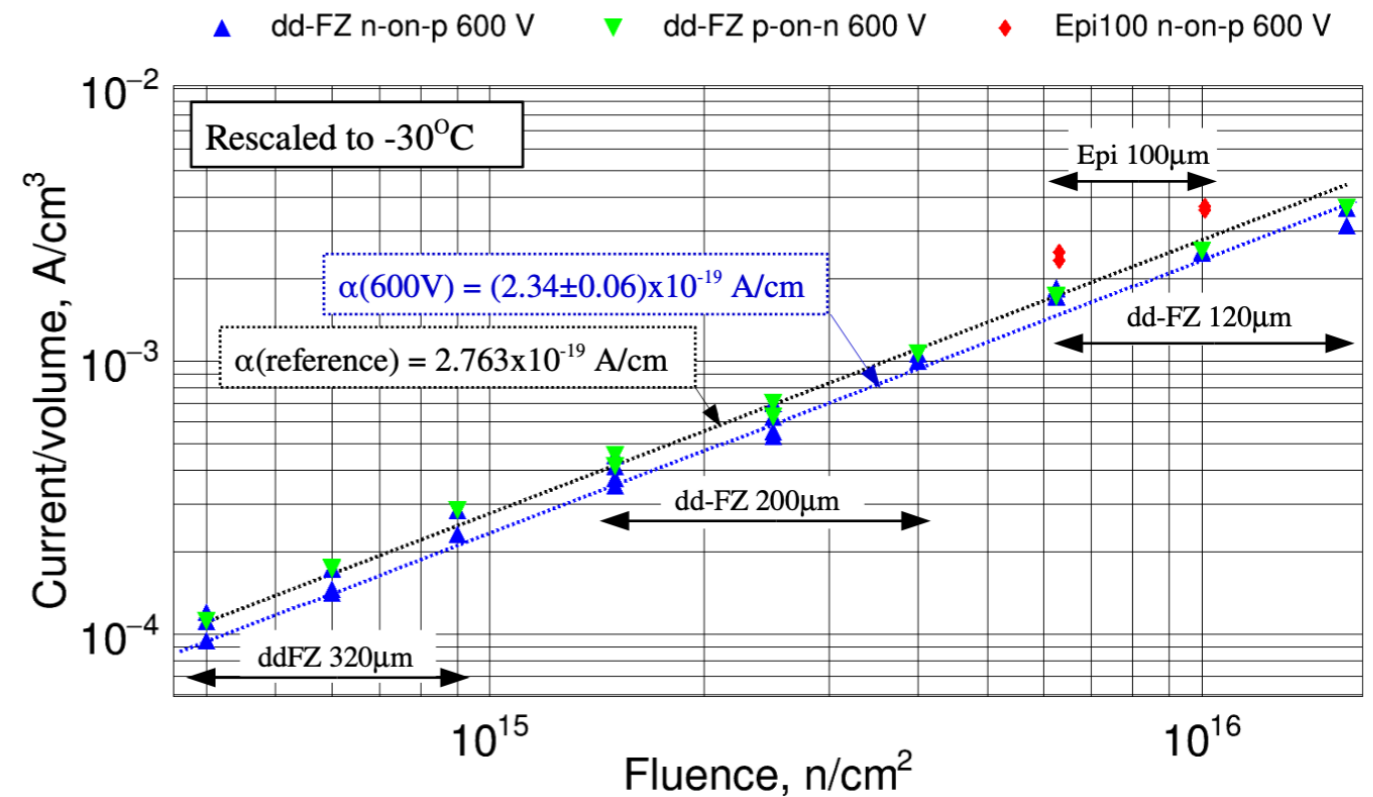
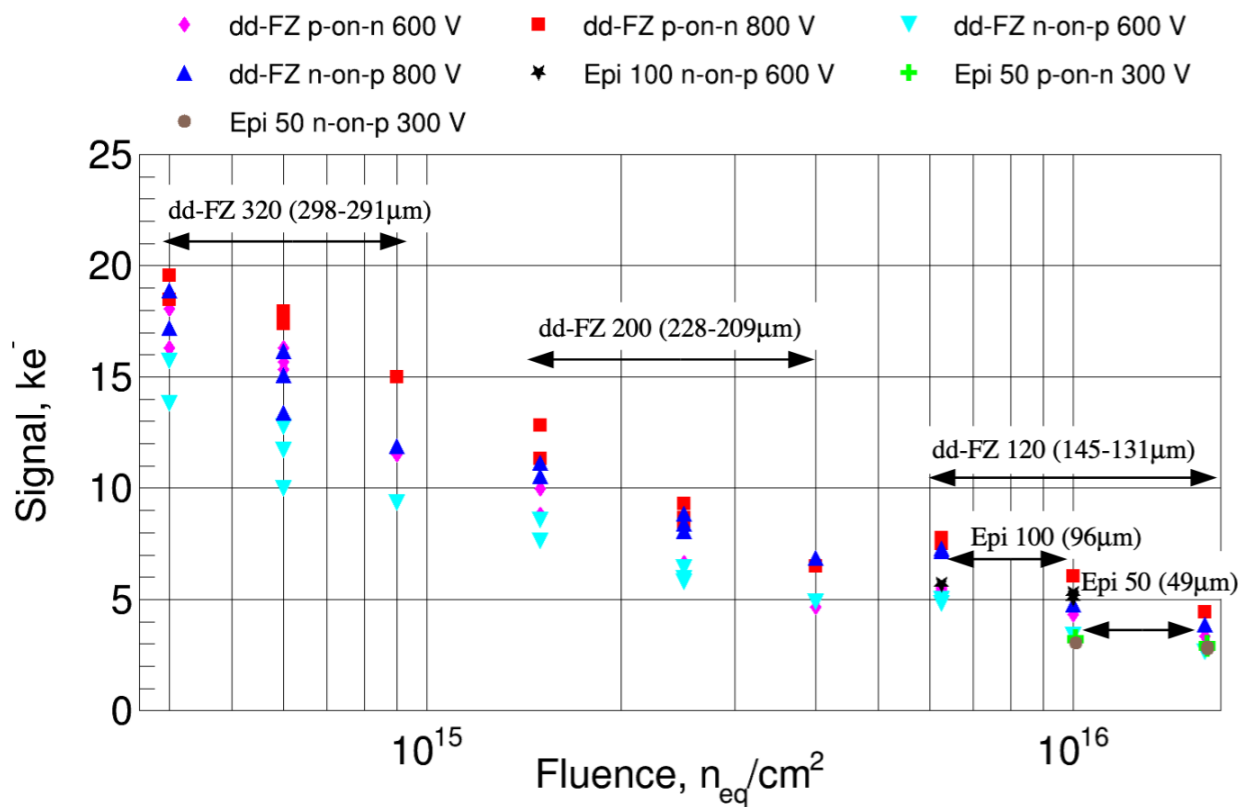


## HD full sensor channel map



# Silicon sensors tolerance

## The Phase-2 Upgrade of the CMS Endcap Calorimeter.



# Silicon sensors property

The Phase-2 Upgrade of the CMS Endcap Calorimeter.

Active thickness ( $\mu\text{m}$ )	Cell size ( $\text{cm}^2$ )	Cell capacitance (pF)	Bulk polarity	Expected range of fluence ( $\times 10^{15} n_{\text{eq}}/\text{cm}^2$ )	Number of wafers	Number of partial wafers
300	1.18	45	p / (n)	0.1–0.5	13 164	1284
200	1.18	65	p	0.5–2.5	8 712	144
120	0.52	50	p	2–7	3 000	324
Total:					24 876	1752

Active thickness ( $\mu\text{m}$ )	<b>300</b>	<b>200</b>	<b>120</b>
Area ( $\text{m}^2$ )	245	181	72
Largest lifetime dose (Mrad)	3	20	100
Largest lifetime fluence ( $n_{\text{eq}}/\text{cm}^2$ )	$0.5 \times 10^{15}$	$2.5 \times 10^{15}$	$7 \times 10^{15}$
Largest outer radius (cm)	$\approx 180$	$\approx 100$	$\approx 70$
Smallest inner radius (cm)	$\approx 100$	$\approx 70$	$\approx 35$
Cell size ( $\text{cm}^2$ )	1.18	1.18	0.52
Initial $S/N$ for MIP	11	6	4.5
Smallest $S/N$ (MIP) after $3000 \text{ fb}^{-1}$	4.7	2.3	2.2



# HGCAL

